

In the Specification

Please amend the title as follows:

~~Semiconductor Constructions And Methods Of Forming Semiconductor Constructions~~

At p. 1, before the "Technical Field" section, please insert:

RELATED PATENT DATA

This patent resulted from a continuation application of U.S. Patent Application Serial No. 10/271,888, which was filed October 15, 2002 and which is a divisional of U.S. Patent Application Serial No. 09/592,604, which was filed June 12, 2000.